Overview

### **HP ZBook Fury 15 G7 Mobile Workstation**



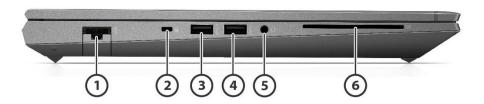
- 1. Ambient Light Sensor
- 2. Internal Microphones (optional)
- 3. Camera LEDs (optional)
- 4. Camera (optional)
- 5. IR Camera (optional)
- 6. Camera Cover (optional)
- 7. Speakers with Discrete Amplifier
- 8. Function Keys (changes with configured options)
- 9. Power button
- 10. HP Programmable Key
- 11. Numeric Keypad
- 12. Pointstick

### Right

- 13. Fingerprint Sensor (optional)
- 14. Touchpad
- 15. 3-button Touchpad
- 16. Indicator LEDs: Power light, Wireless light, Storage usage light
- 17. Power connector
- 18. USB Type-C<sup>®</sup> with Thunderbolt™
- 19. USB Type-C<sup>®</sup> with Thunderbolt™
- 20. Mini DisplayPort™
- 21. HDMI port
- 22. SD Card Reader



### Overview



### Left

- 1. RJ-45
- 2. Nano security lock slot
- 3. USB 3.1 Gen 1 Charging Port

- 4. USB 3.1 Gen 1
- 5. Audio Combo Jack
- 6. Smart Card Reader



### Overview

### At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro <sup>1</sup>, powered by HP's collaboration and connectivity technology.
- Accelerate your workflow. Power through projects with up to 128 GB RAM <sup>2</sup> for fast rendering, editing and visual effects performance.
- Take multitasking to the next level with the Intel<sup>®</sup> Core<sup>™</sup> i9 processor <sup>3</sup> designed to handle complex, multithreaded apps like Adobe<sup>®</sup> Premier Pro, and with fast clock speeds you can boost your speed on single threaded apps like Autodesk 3ds Max.<sup>4</sup>
- Run demanding professional apps with the newest generation Intel® Xeon® processors <sup>5</sup> for powerful performance and productivity.
- Experience high-end visualization and seamlessly render your biggest projects with the next generation NVIDIA® Turing architecture with Quadro® T-Series and RTX graphics<sup>19</sup>; Certified and supported for the apps you use every day.
- Strenuously tested to meet software certification and deliver superb performance with leading software providers, including Autodesk and Adobe® 6.
- Blitz through multiple tasks and ditch external drives with up to 8 TB <sup>7</sup>, local PCIel NVMe storage up to 21x faster than standard HDD and 6x faster than SATA SSD <sup>9</sup>.
- Have confidence with the HP's most secure mobile workstations. Instantly protect against visual hacking with HP Sure View <sup>10</sup>, and defend against firmware and malware attacks with HP Sure Start <sup>11</sup> and HP Sure Sense <sup>12</sup>, and have peace of mind with multi-factor authentication- including an infrared camera and fingerprint scanner <sup>13</sup>.
- Enhanced transfer and upload speeds via dual Thunderbolt™ 3 ports. Get wide-ranging connectivity options to ensure maximum device interaction: USB 3.0, HDMI, mDP, SD card, Smart Card Reader and more.
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H <sup>14</sup> tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock for lightning-fast Thunderbolt™ 3 <sup>15</sup> transfers and the flexibility to run up to two external 4K displays <sup>16,17</sup>.
- Improve connectivity while on Wi-Fi® with HP Extended Range Wireless LAN that allows greater distance from transmission point and fast data throughput at shorter ranges <sup>18</sup>.
- <sup>1</sup> Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- <sup>2</sup> Up to 128GB nECC memory is an optional, configurable feature.
- <sup>3</sup> Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- <sup>4</sup> Adobe Premier Pro and Autodesk 3ds Max sold separately.
- <sup>5</sup> Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- <sup>6</sup> Adobe and Autodesk software sold separately.
- <sup>7</sup> For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 3GB (for Windows 10) of system disk is reserved for system recovery software.
- <sup>9</sup> Speeds based on 8TB PCIe NNVMe storage.
- <sup>10</sup> Based on HP's unique and comprehensive security capabilities at no additional cost among desktop workstation vendors as of Sept. 2017 on HP Mobile Workstations with 7th Gen and higher Intel® Processors.
- <sup>11</sup> HP Sure Start Gen5 is available on select HP PCs with Intel processors. See product specifications for availability.
- <sup>12</sup> HP Sure Sense requires Windows 10. See product specifications for availability.
- <sup>13</sup> Infrared camera and fingerprint scanner are optional, configurable features.
- <sup>14</sup> Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- <sup>15</sup> HP Thunderbolt Dock with Thunderbolt<sup>™</sup> 3 sold separately.



### Overview

- <sup>16</sup> External displays sold separately.
- <sup>17</sup> Optional hybrid graphics is required to run up to two external 4K displays.
- <sup>18</sup> Based on internal testing vs. previous generation product with 802.11ac wireless LAN module.
- <sup>19</sup> The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics

NOTE: See important legal disclosures for all listed specs in their respective features sections.



#### **Features**

### **OPERATING SYSTEM**

Preinstalled OS Windows 10 Pro 64 - HP recommends Windows 10 Pro for business.<sup>1</sup>

Windows 10 Pro for Workstations 641

Windows 10 Home 641

Windows 10 Home Single Language 64<sup>1</sup>

FreeDOS 3.0

Web support OS Red Hat® Enterprise Linux® 82

Ubuntu Linux 20.04<sup>2</sup> Windows 10 Enterprise 64<sup>1</sup>

**Supported Version** HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of

Windows 10, please see: https://support.hp.com/document/c05195282.

### **PROCESSOR**

10<sup>th</sup> Generation Intel® Xeon® W-10885M vPro™ with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB cache, 8 cores)<sup>1,2,3,4,5,6</sup>

10<sup>th</sup> Generation Intel® Core™ i9-10885H vPro™ with Intel® UHD Graphics (2.4 GHz base frequency, up to 5.3 GHz with Intel® Turbo Boost Technology, 16 MB cache, 8 cores) <sup>1,2,3,4,5,6</sup>

10<sup>th</sup> Generation Intel® Core™ i7-10850H vPro™ with Intel® UHD Graphics (2.7 GHz base frequency, up to 5.1 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores) <sup>1,2,3,4,5,6</sup>

10<sup>th</sup> Generation Intel® Core™ i7 10750H with Intel® UHD Graphics (2.6 GHz base frequency, up to 5.0 GHz with Intel® Turbo Boost Technology, 12 MB cache, 6 cores)<sup>1,2,3,4,5</sup>

10<sup>th</sup> Generation Intel® Core™ i5-10400H vPro™ with Intel® UHD Graphics (2.6 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)<sup>1,2,3,4.5,6</sup>

10<sup>th</sup> Generation Intel® Core™ i5 10300H with Intel® UHD Graphics (2.5 GHz base frequency, up to 4.5 GHz with Intel® Turbo Boost Technology, 8 MB cache, 4 cores)<sup>1,2,3,4,5</sup>

<sup>1</sup> Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

<sup>2</sup> Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

<sup>3</sup> Intel® Turbo Poort performance varies depending on bardware, coftware and overall system configuration. Energy Efficient

<sup>3</sup> Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. Energy Efficient Turbo is a power management feature that can lower the maximum core ratio (frequency), if the CPU thinks it can achieve about the same performance as with the maximum turbo frequency. Energy Efficient Turbo feature is disabled in Comet Lake H in order to prioritize performance in DC mode. It can be changed in F10 BIOS settings. See

www.intel.com/technology/turboboost for more information.<sup>4</sup> In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

<sup>5</sup> For full Intel® vPro® functionality, Windows, a vPro supported processor, vPro enabled Q370 chipset or higher and vPro enabled WLAN card are required. Some functionality, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with future "virtual appliances" is yet to be determined.



<sup>&</sup>lt;sup>1</sup> Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <a href="http://www.windows.com">http://www.windows.com</a>.

<sup>&</sup>lt;sup>2</sup> For detailed Linux® OS/hardware support information, see: http/www.hp.com/linux\_hardware\_matrix

### **HP ZBook Fury 15 G7 Mobile Workstation**

# QuickSpecs

**Features** 



**Features** 

### **CHIPSET**

Mobile Intel® WM 490

### INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO/XEON® WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™, Core™ i9 with vPro™ and Xeon® with vPro™ technology is a selectable feature that is available on units configured with select processors, a qualified Intel® WLAN module and a preinstalled Windows® operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off\* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state. 1,2

### **GRAPHICS**

### Integrated

Intel® UHD Graphics 1,2,3,4,5

#### **Discrete**

**NVIDIA Graphic options:** 

NVIDIA® Quadro® RTX 5000 with Max-Q Design (16 GB GDDR6 dedicated) 1,2,3,4,5,7

NVIDIA® Quadro® RTX 4000 with Max-Q Design (8 GB GDDR6 dedicated) 1,2,3,4,5,7

NVIDIA® Quadro® RTX 3000 (6 GB GDDR6 dedicated) 1,2,3,4,5,7

NVIDIA® Quadro® T2000 with Max-Q Design (4 GB GDDR6 dedicated) 1,2,3,4,5

NVIDIA® Quadro® T1000 with Max-Q Design (4 GB GDDR6 dedicated) 1,2,3,4,5

AMD Graphic options:

AMD Radeon Pro W5500M (4 GB GDDR6 dedicated) 1,2,3,4,5,7

AMD Radeon RX 5500M (4 GB GDDR6 dedicated) 1,2,3,4,5,7

<sup>&</sup>lt;sup>7</sup> The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics



<sup>&</sup>lt;sup>1</sup> Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

<sup>&</sup>lt;sup>2</sup> Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™/Core™ i9 with vPro™/Xeon® with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core i7 with vPro™/Core™ i9 with vPro™/XEON® with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

<sup>&</sup>lt;sup>1</sup> UHD content required to view UHD images.

<sup>&</sup>lt;sup>2</sup> Support HD decode, DX11, DX12, HDMI 1.4, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

<sup>&</sup>lt;sup>3</sup> HDMI cable Sold Separately

<sup>&</sup>lt;sup>4</sup> Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

<sup>&</sup>lt;sup>5</sup> miniDP cable sold separately.

<sup>&</sup>lt;sup>6</sup> GPU configurations may be limited to specific panel options

#### **Features**

### **DISPLAY**

#### Non-touch

- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.2 anti-glare WLED-backlit and ambient light sensor 250 nits 45% CG<sup>1,2</sup>
- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 400 nits 72% CG<sup>1,2</sup>
- 15.6" diagonal FHD (1920 x 1080) IPS eDP1.3 + PSR anti-glare WLED-backlit and ambient light sensor 1000 nits 72% CG Next Gen HP SureView Reflect 1,2,5
- 15.6" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 anti-glare BV LED-backlit and ambient light sensor 600 nits 100% DCI-P3 Next Gen HP Dream Color display 1,2,3,4

#### **Touch**

• 15.6" diagonal UHD (3840 x 2160) IPS HDR 400 eDP1.4 + PSR2 WLED-backlit touch screen with Corning® Gorilla® Glass 5 and ambient light sensor 600 nits 100% DCI-P3 1,2,3,4

### HP Virtual Reality<sup>6</sup> Headset (sold separately)

- HP Reverb
- HP Reverb G2

<sup>&</sup>lt;sup>1</sup> UHD content required to view UHD images.

<sup>&</sup>lt;sup>2</sup> Resolutions are dependent upon monitor capability, and resolution and color depth settings.

<sup>&</sup>lt;sup>3</sup> Display options may be limited to specific GPU Configurations.

<sup>&</sup>lt;sup>4</sup> VESA DisplayHDR 400 certifications are pending.

<sup>&</sup>lt;sup>5</sup> HP Sure View Reflect is optional and must be configured at purchase.

<sup>&</sup>lt;sup>6</sup> Virtual Reality content is required to view Virtual Reality images

#### **Features**

### STORAGE AND DRIVES\*

#### **Max Storage**

8TB through four M.2 NVMe drives 6TB through two M.2 NVMe drives and one 2.5" SATA drive

### (up to 1) HDD Storage (SATA 3.2)

500 GB 7200 rpm SATA FIPS 140-2 SED HDD 500 GB 7200 rpm SATA HDD 1 TB 7200 rpm SATA HDD 2 TB 5400 rpm SATA HDD

### (up to 4) M.2 Storage (NVMe™ PCIe SSD)

256 GB PCIe (NVMe<sup>™</sup>) TLC Self Encrypting (SED) Solid State Drive 512 GB PCIe (NVMe<sup>™</sup>) TLC Self Encrypting (SED) Solid State Drive 256 GB PCIe (NVMe<sup>™</sup>) TLC Solid State Drive 512 GB PCIe (NVMe<sup>™</sup>) TLC Solid State Drive 1 TB PCIe (NVMe<sup>™</sup>) TLC Solid State Drive<sup>3</sup> 2 TB PCIe (NVMe<sup>™</sup>) TLC Solid State Drive<sup>3</sup>

### **DRIVE CONTROLLERS**

M.2 Storage Bay (PCIe NVMe)

PCIe Gen 3 x 4 lanes NVMe Solid State Drive

RAID:

RAID 0 and RAID 1 support<sup>1</sup>

### **MEMORY**

Maximum Memory<sup>3,2,5</sup>

128 GB DDR4-2667 non-ECC SDRAM 64 GB DDR4-2667 ECC SDRAM 4 DDR4 SODIMMS<sup>4</sup> Supports Dual Channel Memory<sup>1</sup> Slots are customer accessible / upgradeable

<sup>&</sup>lt;sup>2</sup>Storage slot 1-4 can support NVMe protocol

<sup>&</sup>lt;sup>3</sup>Storage slot 1, 3 and 4 can support SATA protocol

<sup>&</sup>lt;sup>4</sup>Only storage slots 1-3 can support RAID

<sup>\*</sup> For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

<sup>&</sup>lt;sup>1</sup> Support only available with 1TB + 1TB M.2 storage or 2TB + 2TB M.2 storage combinations

<sup>&</sup>lt;sup>2</sup> Not available if slots if storage slots 3 or 4 are selected

<sup>&</sup>lt;sup>1</sup>Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

<sup>&</sup>lt;sup>2</sup> Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

<sup>&</sup>lt;sup>3</sup>Transfer rates up to 2667 MT/s for nECC and ECC memory combinations when memory suppliers are consistent. If suppliers are not consistent, speeds may drop to 2133 MT/s for nECC and 2400 MT/s for ECC memory combinations. A custom configuration including part number AY104AV can be used to lock in a consistent vendor.

<sup>&</sup>lt;sup>4</sup> Intel® allows architectures designed with four DIMM slots to run at 2400 MT/s

<sup>&</sup>lt;sup>5</sup> Maximum memory capacities assume Windows 64-bit operating systems. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

#### **Features**

### **NETWORKING/COMMUNICATIONS**

#### I AN

Intel® I219-LM GbE, vPro™
Intel® I219-V GbE, non-vPro™

<sup>1</sup>GbE - The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

#### **WLAN**

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, vPro<sup>™ 1</sup>
Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, non-vPro<sup>™ 1</sup>

<sup>1</sup>Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

#### WWAN1

Intel® XMM™ 7360 LTE Advanced CAT 9

Nano SIM card slot<sup>2</sup>

<sup>1</sup> WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

### **Optional Near Field Communication (NFC) module**

### **AUDIO/MULTIMEDIA**

#### Audio

Audio by Bang & Olufsen, dual stereo speakers, HP World Facing Microphone dual array digital microphone<sup>1</sup>, functions keys for volume up and down, combo microphone/headphone jack, HD audio

<sup>1</sup>Dual-microphone array when equipped with optional webcam and optional world facing microphone.

#### Camera<sup>1, 2, 3</sup>

720p HD webcam with IR 720p HD webcam



<sup>&</sup>lt;sup>2</sup> All units have an internal SIM card slot but 'For WWAN' base units ship with antennas.

<sup>&</sup>lt;sup>1</sup> FHD and HD content required to view HD images respectively.

<sup>&</sup>lt;sup>2</sup> Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

<sup>&</sup>lt;sup>3</sup>Camera-configured options come with a Privacy Shutter

#### **Features**

### **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS**

### Keyboard

HP Premium Quiet Keyboard, full-size, spill-resistant, backlit, a Programmable Key, with sperate numeric keypad, HP DuraKey, touchpad with glass surface, multi-touch gestures and taps enabled

### **Pointing Devices**

Dual pointstick; Touchpad with multi-touch gestures enabled, taps enabled as default; Microsoft Precision Touchpad Default Gestures Support

### SOFTWARE AND SECURITY

#### **Workstation ISV Certifications**

See the latest list of certifications at: http://www.hp.com/go/isv

#### **HP ZCENTRAL REMOTE BOOST SOFTWARE**

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

#### **HP Performance Advisor**

HP Performance Advisor enables optimal configuration of HP Mobile Workstations delivering stability and best performance. HP Performance Advisor will guide your system setup allowing a "custom" configuration that best matches the workstation to user requirements. Download at: http://www.hp.com/go/performanceadvisor

#### **Software**

Bing search for IE11

**Buy Office** 

**HP Hotkey Support** 

**HP** Image Assistant

**HP Noise Cancellation Software** 

HP Performance Advisor8

**HP Sure Recover** 

HP ZCentral Remote Boost<sup>2</sup>

HP Support Assistant <sup>1,7</sup>

Native Miracast support 4

HP Connection Optimizer9

**HP Cloud Recovery** 

myHP

#### **Security Management**

Absolute persistence module 6

### **HP Admin**

**HP Device Access Manager** 

**HP FingerPrint Sensor** 

HP Manageability Integration Kit Gen4<sup>11</sup>

**HP Power On Authentication** 

Security lock slot12

Trusted Platform Module TPM 2.0 Embedded Security Chip with Windows 10 (Common Criteria EAL4+ Certified)(FIPS 140-2 Level 2 Certified)

Master Boot Record security

Pre-boot authentication

Windows Defender<sup>10</sup>

HP Client Security Manager Gen57, 16

HP BIOSphere Gen6 5

HP Sure Recover Gen3<sup>13</sup>



#### **Features**

HP Sure Start Gen6 5, 14

HP Secure Erase 15

HP Sure Sense<sup>17</sup>

HP Secure Platform<sup>18</sup>

**HP Sure Click** 

HP Sure Run Gen3

**HP Tamper Lock** 

**HP SureView Reflect** 

Smartcard Reader - Alcor AU9560 (FIPS 201 Compliant)

#### **BIOS Version**

ISO/IEC 19678: 2015 (formerly NIST 800-147) compliant

UEFI version: 2.7

### For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

- <sup>1</sup> HP Support Assistant Requires Windows and Internet Access.
- <sup>2</sup> HP Z Central Remote Boost Software does not come preinstalled on Z Workstations but can be downloaded and run on all Z desktop and laptops without license purchase. With non-Z sender devices, purchase of perpetual individual license or perpetual floating license per simultaneously executing versions and purchase of ZCentral Remote Boost Software Support is required. RGS requires Windows, RHEL (7 or 8), UBUNTU 18.04 LTS, or HP ThinPro 7 operating systems. MacOS (10.13 or newer) operating system is only supported on the receiver side. Requires network access. The software is available for download at hp.com/ZCentralRemoteBoost.<sup>4</sup> Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast.
- <sup>5</sup> HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations. <sup>6</sup> Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- <sup>8</sup> HP Performance Advisor Software HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www8.hp.com/us/en/workstations/performance-advisor.html <sup>9</sup> HP Connection Optimizer requires Windows 10.
- <sup>10</sup> Microsoft Defender Opt in and internet connection required for updates.
- 11 HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- <sup>12</sup> Nano Security lock slot is Lock sold separately.
- <sup>13</sup> HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover (Gen1) does not support platforms with Intel<sup>®</sup> Optane™.
- <sup>14</sup> HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.
- <sup>15</sup> For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- <sup>16</sup> HP Client Security Manager Gen5 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.
- <sup>17</sup> HP Sure Sense requires Windows 10. See product specifications for availability.
- <sup>18</sup> Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.



#### **Features**

### **POWER**

#### **Power Supply**

Up to 16 hours 15 minutes1

HP Long Life 8-cell, 94 Wh Li-ion polymer<sup>2</sup>

120 W Slim Smart external AC power adapter 150 W Slim Smart external AC power adapter 200 W UltraSlim Smart external AC power adapter

120 W power adapter is configurable with Intel UMA graphics

150 W power adapter is configurable with NVIDIA Quadro T1000 and T2000 configurations

200 W power adapter is configurable with NVIDIA Quadro RTX 30003 or higher configurations

### **ENVIRONMENTAL**

ENERGY STAR® certified and EPEAT® 2.0 registered where applicable. EPEAT® registration varies by country. See www.epeat.net for registration status by country. 1

Low halogen<sup>2</sup>



<sup>&</sup>lt;sup>1</sup> Measured with MobileMark 14

<sup>&</sup>lt;sup>2</sup> Serviceable by warranty. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year.

<sup>&</sup>lt;sup>3</sup> The HP custom vapor chamber (Z VaporForce) is only available on configurations with NVIDIA RTX graphics or AMD Radeon graphics

<sup>&</sup>lt;sup>1</sup> Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

<sup>&</sup>lt;sup>2</sup> External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

#### **Features**

### **WEIGHTS & DIMENSIONS**

**Dimensions (w x d x h)** 35.7 x 24.25 x 2.59 cm 14.06 x 9.55 x 1.02 in

#### Weights

Starting at 2.35kg (5.18 lb)

Weight varies by configuration and components.

A deck: Anodized Aluminum

B deck: Aluminum with plastic antenna cover; Touch has Corning® Gorilla ® Glass 5

C deck: Anodized Aluminum D deck: Magnesium Die Cast E door: Magnesium Die Cast

**Metal Alloy Hinges** 

### **PORTS/SLOTS**

1 smart card reader 1 SD 4.0 Media Card Reader

#### Left side<sup>6</sup>

1 RJ-45

1 USB 3.1 Gen 1 (charging)

1 USB 3.1 Gen 1

1 headphone/microphone combo

### Right side<sup>6</sup>

1 power connector 2 USB Type-C® (Thunderbolt™ 3, pass through support DispalyPort™ 1.4², USB 3.1 Gen 2, with BC 1.2) 1 Mini DisplayPort™ 1.4 1 HDMI 2.0b<sup>1,3,4,5</sup>

- <sup>1</sup> HDMI port-cable not included.
- <sup>2</sup> Mini DisplayPort™ 1.4 with discrete, 1.2 with UMA.
- <sup>3</sup> HDMI 2.0b with discrete, 1.4 with UMA.
- <sup>4</sup> When both USB Type-C® are in use, HDMI cannot be detected
- <sup>5</sup> When one USB Type-C<sup>®</sup> is in use, HDMI can be detected if USB Type-C<sup>®</sup> in use is assigned to different channel
- <sup>6</sup> When product is under heavy power loading, performance may be reduced to prevent battery drain. Disconnecting USB devices will restore system performance

### **SERVICE AND SUPPORT**

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life batteries which will have same 1-year or 3-year limited warranty as the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.

<sup>1</sup>Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are



### **Features**

governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



### Technical Specifications – System Unit

### **SYSTEM UNIT**

**Stand-Alone Power Nominal Operating** 19.5V

Requirements (AC Power) Voltage

**Average Operating** System in idle mode + max Adapter Safety test

**Power(idle)** panel brightness condition

Discrete Graphics 80W
Max Operating Power <200W

**Temperature Operating** 41° to 122° F (5° to 50° C) (reading optical)

'41° to 113° F (5° to 45° C) (writing optical)

Non-operating 40° to 140° F (-40° to 60° C)

Operating 10% to 90%, non-condensing

**Non-operating** 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating 40 G, 2 ms, half-sine

**Non-operating** 200 G, 2 ms, half-sine

**Random Vibration Operating** 0.75 grms **Non-operating** 1.50 grms

Maximum Altitude (unpressurized)

Planned Industry Standard Certifications

**Relative Humidity** 

Operating -50 to 10,000 ft. (-15.24 to 3,048 m)
Non-operating -50 to 15,000 ft. (-15.24 to 12,192 m)

UL Yes
CSA Yes
FCC Compliance Yes
ENERGY STAR® Yes
EPEAT® Yes
ICES Yes
Australia / NZ A-Tick Compliance

CCCYes Japan VCCI Compliance Yes KCC Yes **BSMI** Yes **CE Marking Compliance** Yes MIL STD 810H Yes **BNCI or BELUS** Yes GOST Yes Saudi Arabian

Compliance (ICCP)

Ves

UKRSERTCOMPUTER

Yes



<sup>&</sup>lt;sup>1</sup>Configurations of the HP ZBook Fury 15 G7 that are ENERGY STAR® qualified are identified as HP ZBook Fury 15 G7 ENERGY STAR® on HP websites and on http://www.energystar.gov.

<sup>&</sup>lt;sup>2</sup> EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at www.hp.com/go/options.

Technical Specifications – Displays

### **DISPLAYS**

15.6" diagonal FHD IPS eDP1.2 anti-glare WLEDbacklit and ambient light sensor 250 nits 45% CG (1920 x 1080)

Outline Dimensions (W x H) 399.95 x 251.01 mm (max) **Active Area** 381.89 x 214.81 mm

Weiaht 550 g (max) **Diagonal Size** 15.6 inch **Thickness** 4.0 mm (max) Interface eDP 1.2 **IPS** Panel Technology **Surface Treatment** Anti-Glare

**Touch Enabled** Nο **Refresh Rate** 60 hrz **Brightness** 400 nits

**Pixel Resolution Format** 1920 x 1080 (FHD)

> Configuration **RGB**

**Backlight LED** 127 45% CG **Color Gamut Coverage** Color Depth 6 bits + Hi FRC **Viewing Angle** UWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

15.6" diagonal FHD IPS eDP1.3 + PSR anti-glare **WLED-backlit and** ambient light sensor 400 nits 72% CG (1920 x 1080)

Outline Dimensions (W x H) 399.95 x 251.01 mm (max) **Active Area** 381.89 x 214.81 mm

Weight 550 g (max) **Diagonal Size** 15.6 inch **Thickness** 4.0 mm (max) eDP 1.3 + PSR

**IPS Panel Technology Surface Treatment** Anti-Glare

Interface

**Touch Enabled** No **Refresh Rate** 60 hrz **Brightness** 400 nits

1920 x 1080 (FHD) **Pixel Resolution Format** 

> Configuration **RGB**

Backlight LED PPI 127 **Color Gamut Coverage** 72% CG **Color Depth** 6 bits + Hi FRC Viewing Angle UWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



### Technical Specifications – Displays

Next Gen HP SureView
Reflect 15.6" diagonal
FHD IPS eDP1.3 + PSR
anti-glare WLED-backlit
and ambient light sensor
1000 nits 72% CG (1920 x Thickness
1080)
Unterface

Outline Dimensions (W x H) 398.6 x 253 mm (max) (w/ bracket & PCB)

**Active Area** 382.12 x 214.94 mm

 Weight
 550 g (max)

 Diagonal Size
 15.6 inch

 Thickness
 4.0 mm (max)

 Interface
 eDP 1.3 + PSR

Panel Technology IPS
Surface Treatment Anti-Glare

Touch Enabled No

Contrast Ratio 1000:1 (typ.)
Refresh Rate 60Hz

Brightness 1000 nits

Pixel Resolution Pitch 1920 x 1080 (FHD)

Format RGB

BacklightLEDPPI254Color Gamut Coverage72% CGColor Depth8 bits

Viewing Angle UWVA 85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Next Gen HP Dream Color Outline Dimer display 15.6" diagonal Active Area UHD IPS HDR 400 eDP1.4 + PSR2 anti-glare BV Weight LED-backlit and ambient Diagonal Size light sensor 600 nits Thickness 100% DCI-P3 (3840 x Interface 2160)

Next Gen HP Dream Color Outline Dimensions (W x H) 398.6 x 253 mm (max) (w/ bracket & PCB)

**Active Area** 382.12 x 214.94 mm

 Weight
 550 g (max)

 Diagonal Size
 15.6 inch

 Thickness
 4.0 mm (max)

 Interface
 eDP 1.4 + PSR2

Panel Technology IPS
Surface Treatment Anti-Glare

**Touch Enabled** No

Contrast Ratio 1000:1 (typ.)

Refresh Rate 60Hz
Brightness 600 nits

Pixel Resolution Pitch 3840 x 2160 (UHD)

Format RGB

Backlight LED PPI 254

**Color Gamut Coverage** 100% DCI-P3 **Color Depth** 8 bits

Viewing Angle UWVA 85/85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.



### Technical Specifications – Displays

15.6" diagonal UHD IPS
HDR 400 eDP1.4 + PSR2
WLED-backlit touch
screen with Corning®
Gorilla® Glass 5 and
ambient light sensor 600
Thickness
nits 100% DCI-P3 (3840 x
2160)
Outline Diagonal S
Active Are
Weight
Diagonal S
Interface

Outline Dimensions (W x H) 398.6 x 253 mm (max) (w/ bracket & PCB)

**Active Area** 382.12 x 214.94 mm

 Weight
 550 g (max)

 Diagonal Size
 15.6 inch

 Thickness
 4.0 mm (max)

 Interface
 eDP 1.4 + PSR2

Panel Technology IPS

**Surface Treatment** Gorilla Glass 5 with Anti-Glare

Touch Enabled No

Contrast Ratio 1000:1 (typ.)

Refresh Rate60HzBrightness600 nits

**Pixel Resolution** Pitch 3840 x 2160 (UHD)

Format RGB

Backlight LED PPI 254

**Color Gamut Coverage** 100% DCI-P3

**Color Depth** 8 bits

Viewing Angle UWVA 85/85/85

All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Anti-Glare surface treatment only available with non-touch option



### Technical Specifications – Storage

Capacity

### STORAGE AND DRIVES

256GB PCIe NVMe TLC M.2 Form Factor 2280 Solid State Drive

M.2 2280 **Drive Weight** 0.02 lb (10 q) 256GB Generation 1100 **NAND Type** TLC

Height 2.6 mm Max Width 0.87 in (22 mm) Interface ACS-3, SATA 3.2

**Performance Maximum Sequential Read Maximum Sequential Write** 

> 3500 MB/s 2200 MB/s

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

256GB PCIe NVMe TLC M.2 Form Factor 2280 SED Opal 2 Solid **State Drive** 

M.2 2280 **Drive Weight** 0.02 lb (10 q) Capacity 256GB Generation 1100 **NAND Type** TLC

Height 2.6 mm Max Width 0.87 in (22 mm) Interface ACS-3. SATA 3.2

**Performance Maximum Sequential Read Maximum Sequential Write** 

> 3000 MB/s 1600 MB/s

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2280 Solid State Drive

512GB PCIe NVMe TLC M.2 Form Factor M.2 2280 **Drive Weight** 0.02 lb (10 q) Capacity 512GB Generation 1100 **NAND Type** TLC

Height 2.6 mm Max Width 0.87 in (22 mm) Interface ACS-3, SATA 3.2

**Performance Maximum Sequential Read Maximum Sequential Write** 

> 3400 MB/s 2956 MB/s



### Technical Specifications – Storage

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

512TB PCIe NVMe TLC M.2 Form Factor 2280 SED Opal 2 Solid Drive Weight

2280 SED Opal 2 Solid Drive Wei State Drive Capacity

Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 512GB

Generation 1100

NAND Type TLC

 Height
 2.6 mm Max

 Width
 0.87 in (22 mm)

 Interface
 ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

3400 MB/s 2500 MB/s

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

1TB PCIe NVMe TLC M.2 2280 Solid State Drive Form Factor M.2 2280

Drive Weight 0.02 lb (10 g)

Capacity 1TB NAND Type TLC

Height2.6 mm MaxWidth0.87 in (22 mm)InterfaceACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

3480 MB/s 2800 MB/s

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Available in RAID 1 config Yes

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2TB PCIe NVMe TLC M.2 2280 Solid State Drive 
 Form Factor
 M.2 2280

 Drive Weight
 0.02 lb (10 g)

Capacity 2TB NAND Type TLC

**Height** 2.6 mm Max

### Technical Specifications – Storage

Width 0.87 in (22 mm)
Interface ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

3180 MB/s 2920 MB/s

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

Available in RAID 1 config Yes

**Note:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

**500GB SATA 2.5" HDD** Form Factor 2.5"

 Drive Weight
 0.02 lb (10 g)

 Capacity
 500GB

 Generation
 1100

 Height
 2.6 mm Max

 Width
 0.87 in (22 mm)

 Interface
 ACS-3. SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

**Notes:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

500GB SATA 2.5" SED HDD - FIPS-140-2 Form Factor 2.5"

 Drive Weight
 0.02 lb (10 g)

 Capacity
 500GB

 Generation
 1100

 Height
 2.6 mm Max

 Width
 0.87 in (22 mm)

 Interface
 ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

**Notes:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

1TB SATA 2.5" HDD Form Factor 2.5"

**Drive Weight** 0.02 lb (10 g)



### Technical Specifications – Storage

Capacity 1TB
Generation 1100

 Height
 2.6 mm Max

 Width
 0.87 in (22 mm)

 Interface
 ACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

**Notes:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.

2TB SATA 2.5" HDD Form Factor 2.5"

**Drive Weight** 0.02 lb (10 g)

Capacity2TBGeneration1100Height2.6 mm MaxWidth0.87 in (22 mm)InterfaceACS-3, SATA 3.2

Performance Maximum Sequential Read Maximum Sequential Write

530 400

**Logical Blocks** 1,000,215,216

**Operating Temperature** 32° to 158°F (0° to 70°C) [ambient temp]

**Features** ATA Security; TCG Opal 2.0; FIPS

DIPM; TRIM; DEVSLP

**Notes:** For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for

system recovery software.



### Technical Specifications – Networking

### **NETWORKING/COMMUNICATION**

Intel i219LM 10/100/1000 Integrated NIC **Connector** RJ-45

**System Interface** PCI(Intel proprietary) + SMBus

Data rates supported 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)

1000 Mbit/s operation (1000BASE-T; IEEE 802.3d; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

**Performance** TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

**Power consumption** Cable Disconnetion: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

**Power** ACPI compliant – multiple power modes

Management Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface

Auto MDI/MDIX Crossover cable detection

IT Manageability

Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

Intel i219v 10/100/1000 Connector Integrated NIC System Int

**Connector** RJ-45

**System Interface** PCI(Intel proprietary) + SMBus

**Data rates supported** 10 Mbit/s operation (10BASE-T; IEEE 802.3; IEEE 802.3 clauses 13-14)

100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)

Auto-Negotiation (Automatic Speed Selection)

Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100

Mbit/s

IEEE Compliance IEEE 802.1p QoS (Quality of Service) Support

IEEE 802.1q VLAN support



### Technical Specifications – Networking

IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)

IEEE 802.3az EEE (Energy Efficient Ethernet)

**Performance** TCP/IP/UDP Checksum Offload (configurable)

Protocol Offload (ARP & NS)

Large send offload and Giant send offload

Receiving Side Scaling Jumbo Frame 9K

**Power consumption** Cable Disconnetion: 25mW

100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW

**Power** ACPI compliant – multiple power modes

**Management** Situation-sensitive features reduce power consumption

Advanced link down power saving for reducing link down power

consumption

Management Interface Auto MDI/MDIX Crossover cable detection

IT Manageability Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft

Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)

PXE 2.1 Remote Boot

Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x,

clause 30))

Comprehensive diagnostic and configuration software suite

Virtual Cable Doctor for Ethernet cable status

#### NFC (Near Field Communication) module (optional)

Dimensions (LxW

**x H)** Module 50 mm by 23 mm by 2.89 mm **Chipset** SiM3U156+SiM3U154+AMS3911

**System interface** USB 2.0

**System interface (I/O)** Audio signal output on card read

NFC RF standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693

ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4 in reading CSN

Reader Mode 13.56MHz:

ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa

FeliCa Topaz cards HID iClass ISO 125kHz: HID Prox UID AWID UID



### Technical Specifications – Networking

**CASI-RUSCO UID** EM 410x UID

Indana ASP/ASP+ UID

Frequency 13.56MHz and 125kHz

**NFC Modes Supported** Reader

**Raw RF Data Rates** 106, 212 kbps

Operating

-30°C to 70°C temperature Storage temperature -40°C to 80°C

**Humidity** 10-90% operating 5-95% non-operating

**Supply Operating** 

4.35 to 5.25 Volts voltage

**Power Consumption** Mode Power Consumption, Typical

> **Polling** 75mA **Comunication** 85mA

**Antenna** 13.56MHz/125kHz combo antenna. Antenna connector, 0.5mm pitch, 16pin

connector FPC.

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, nonvPro, supporting gigabit file transfer speeds)

non-vPro

**Wireless LAN Standards** IEEE 802.11a

> IEEE 802.11b IEEE 802.11q IEEE 802.11n IEEE 802.11ac IEEE 802.11ax IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i

IEEE 802.11k IEEE 802.11r IEEE 802.11v Wi-Fi certified

Interoperability **Frequency Band** 802.11b/g/n/ax

> • 2.402 – 2.482 GHz 802.11a/n/ac/ax • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 - 5.35 GHz • 5.47 – 5.725 GHz

• 5.825 – 5.850 GHz

**Data Rates** • 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz

& 160MHz)



### Technical Specifications – Networking

**Modulation** Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

Security<sup>1</sup> • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/q

mode only

• AES-CCMP: 128 bit in hardware

802.1x authentication

• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationIEEE 802.11i

WAPI

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

**Roaming** IEEE 802.11 compliant roaming between access points

Output Power<sup>2</sup>
• 802.11b: +18.5dBm minimum
• 802.11g: +17.5dBm minimum

• 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
 802.11n HT40(2.4GHz): +14.5dBm minimum
 802.11n HT20(5GHz): +15.5dBm minimum
 802.11n HT40(5GHz): +14.5dBm minimum

• 802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption • Transmit mode 2.0 W

• Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode 50 mW (WLAN unassociated)

• Connected Standby 10mW

Radio disabled 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity**<sup>3</sup> •802.11b, 1Mbps : -93.5dBm maximum

•802.11b, 11Mbps: -84dBm maximum •802.11a/g, 6Mbps: -86dBm maximum •802.11a/g, 54Mbps: -72dBm maximum •802.11n, MCS07: -67dBm maximum •802.11n, MCS15: -64dBm maximum

802.11ac, MCS0: -84dBm maximum
 802.11ac, MCS9: -59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

**Antenna Type** High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

**Dimensions** 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

### Technical Specifications – Networking

**Weight** 1. Type 2230 : 2.8g

2. Type 126: 1.3g

**Operating Voltage** 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber - Radio Off; LED Off - Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band 2402 to 2480 MHz

**Number of Available Channels** Legacy : 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

**Data Rates and Throughput** Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

**Power Consumption** Peak (Tx): 330 mW

Peak (Rx): 230 mW Selective Suspend: 17 mW

**Bluetooth Software Supported** 

**Link Topology** 

Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328. ETS 300 826

Certifications Low Voltage Directive IEC950

UL, CSA, and CE Mark

**Bluetooth Profiles Supported** BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 —Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



### Technical Specifications - Networking

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, vPro, supporting gigabit file transfer speeds)	Wireless LAN Standards	IEEE 802.11a
		IEEE 802.11b
	:	IEEE 802.11g
		IEEE 802.11n
vPro		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n/ax
		• 2.402 – 2.482 GHz
		802.11a/n/ac/ax
		• 4.9 – 4.95 GHz (Japan)
		• 5.15 – 5.25 GHz
		• 5.25 – 5.35 GHz
		• 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
	Data Datas	
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
		• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		<ul> <li>802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps</li> <li>802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)</li> </ul>
		• 802.11ac: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &
		160MHz)
		• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz
		& 160MHz)
	Modulation	Direct Sequence Spread Spectrum
	riouutation	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
		, 1024QAM
	Security <sup>1</sup>	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g
	5 ccy	mode only
		AES-CCMP: 128 bit in hardware
		802.1x authentication
		<ul> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> </ul>
		WPA2 certification
		• IEEE 802.11i
		• WAPI
	<b>Network Architecture</b>	Ad-hoc (Peer to Peer)
	Models	Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power <sup>2</sup>	• 802.11b: +18.5dBm minimum
		• 802.11g : +17.5dBm minimum
		• 802.11a : +18.5dBm minimum
		002 44 - UT20/2 4CU-) - 145 5 dD

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum

### Technical Specifications – Networking

802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ax HT40(2.4GHz): +10dBm minimum
802.11ax VHT160(5GHz): +10dBm minimum

**Power Consumption** • Transmit mode :2.0 W

• Receive mode: 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)
Idle mode :50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

**Power Management** ACPI and PCI Express compliant power management

802.11 compliant power saving mode

**Receiver Sensitivity**<sup>3</sup> •802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum
802.11ac, MCS0: -84dBm maximum
802.11ac, MCS9: -59dBm maximum
802.11ax, MCS11(HT40): -59dBm maximum
802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna Type High efficiency antenna with spatial diversity, mounted in the

display enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth

communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

**Dimensions** 1. Type 2230 : 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

**Weight** 1. Type 2230 : 2.8g

2. Type 126: 1.3g

**Operating Voltage** 3.3v +/- 9%

**Temperature** Operating 14° to 158° F (-10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

**Humidity** Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating Non- 0 to 10,000 ft (3,048 m)

operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Frequency Band 2402 to 2480 MHz

**Number of Available Channels** Legacy : 0~79 (1 MHz/CH)

BLE: 0~39 (2 MHz/CH)

**Data Rates and Throughput** Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps

BLE: 1 Mbps data rate; throughput up to 0.2 Mbps

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,

voice channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)



### Technical Specifications – Networking

**Transmit Power** The Bluetooth component shall operate as a Class II Bluetooth

device with a maximum transmit power of + 9.5 dBm for BR and

EDR.

**Power Consumption** Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

**Bluetooth Software Supported** 

**Link Topology** 

Microsoft Windows Bluetooth Software

**Power Management** Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

**Power Management** ETS 300 328, ETS 300 826 **Certifications** Low Voltage Directive IEC950

UL, CSA, and CE Mark

**Bluetooth Profiles Supported** BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 —Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

#### Intel® XMM™ 7360 LTE-Advanced CAT9 (Pandora)\*

Technology/Operating bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100

(Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

 ${\tt 3GPP\,Release\,11\,LTE\,Specification\,CAT.9,\,DL\,60MHz\,BW\,throughput\,up\,to\,450Mbps;\,UL\,20MHz}$ 

throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

**GPS** Standalone, A-GPS (MS-A, MS-B)

**GPS bands** 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

### Technical Specifications – Networking

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

> DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

LTE: 23 dBm Maximum output power

HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

**Form Factor** M.2, 3042-S3 Key B

Weight 5.8 q

**Dimensions** 42 x 30 x 2.3 mm

(Length x Width x Thickness)

### **Near Field Communications Controller (optional)**

Dimensions (L x W

x H) Module 25 mm by 10 mm by 2.0 mm

**NPC100** Chipset System interface 120

**NFC RF standards** ISO/IEC 14443 A

> ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

**NFC Forum Support** Reader (PCD-VCD)

Mode(1)

Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2 ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693

MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC- ISO/IEC 14443 A

VICC) Mode(1) ISO/IEC 14443 B and B'

> **MIFARE** FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer **Raw RF Data Rates** 106, 212, 424, 848 kbps

Operating

0°C to 70°C temperature Storage temperature -20°C to 125°C **Humidity** 10-90% operating

5-95% non-operating



<sup>\*</sup> Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

### Technical Specifications - Networking

Supply Operating

**voltage** 4.35 to 5.25 Volts **I/O Voltage** 1.8V or 3.3V

Power Consumption Booster enable,

VCC\_BOOST = 5V) Polling
Mode Power
Consumption, Tag Typ
Typical Percent

VBAT= 3.3V, **Polling** 7.3 mA

Detected Test Total 283.8 mA
Tag Type 1 Net Module 236.8 mA
Detected Test Total 288.8 mA
Tag Type 2 Net Module 241.8 mA

Detected TestTotal 287.7 mATag Type 3Net Module 240.7 mADetected TestTotal 282.3 mATag Type 4Net Module 235.3 mA

Antenna Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is

external to module.



### Technical Specifications – Power

### **POWER**

120 Watt Slim Smart AC Adapter 
 Dimensions
 138x68.5x25.4mm

 Weight
 unit: 350g +/- 10g

Input Input Efficiency 88% at 115 Vac and 89% at 230Vac

**Input frequency** 47 ~ 63 Hz

range

**Input AC current** 1.7 A at 90 Vac and Maximum Load

Output Output power 120W

**DC output** 19.5V

**Hold-up time** 5ms at 115 Vac input

Output current limit <18.0A

Connector C5

Environmental Design Operating

temperature

32° to 95° F (0° to 35° C)

Non-operating

(storage) temperature

Altitude

-4° to 185° F (-20° to 85° C)

0 to 16,400 ft (0 to 5,000 m)

Humidity5% to 95%Storage Humidity5% to 95%

**EMI and Safety Certifications** Eg:

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

2.7 A at 90 Vac and Maximum Load

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200,000 hours at 25°C ambient condition.

### 150 Watt Slim Smart AC Adapter

 Dimensions
 138x66x22mm

 Weight
 unit: 325g +/- 10g

**Input Efficiency** 88% at 115 Vac and 89% at 230 Vac

**Input frequency** 47 ~ 63 Hz

range

Output Output power 150W

DC output 19.5V

**Hold-up time** 5ms at 115 Vac input

Output current limit <16.0A

**Connector** C5

**Environmental Design** Operating 32° to 95° F (0° to 35° C)

**Input AC current** 

temperature



<sup>\*</sup>Can only be configured with Intel UMA Graphics option

### Technical Specifications – Power

**Non-operating** -4° to 185° F (-20° to 85° C)

(storage) temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 5% to 95% **Storage Humidity** 5% to 95%

**EMI and Safety Certifications** Eg:

\*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 200,000 hours at 25°C ambient condition.

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\*Can only be configured with Quadro T1000 and T2000 Graphics option

### 200 Watt UltraSlim Smart AC Adapter

 Dimensions
 152x73x23.5mm

 Weight
 unit: 530g +/- 10g

**Input Input Efficiency** 88% at 115 Vac and 89% at 230Vac

**Input frequency range** 47 ~ 63 Hz

**Input AC current** 2.9 A at 90 Vac and Maximum Load

Output Output power 200W

**DC output** 19.5V

**Hold-up time** 5ms at 115 Vac input

Output current limit <16.0A

**Connector** C13

**Environmental Design** Operating 32° to 95° F (0° to 35° C)

temperature

Non-operating (storage) -4° to 185° F (-20° to 85° C)

temperature

**Altitude** 0 to 16,400 ft (0 to 5000m)

**Humidity** 5% to 95% **Storage Humidity** 5% to 95%

**EMI and Safety** Eg

**Certifications** \*CE Mark - full compliance with LVD and EMC directives

\* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC

Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

\* MTBF - over 100,000 hours at 25°C ambient condition.

\*Can only be configured with Quadro RTX3000, RTX4000, RTX5000 Graphics and Radeon W5500M, RX 5500M Graphics option



### Technical Specifications – Power

HP Long Life 8-cell Polymer (94Wh) Battery **Cells/Type** 8 cell

**Energy** Voltage 11.55V

Amp-hour capacity 4.15Ah

**Temperature** Operating (Charging) 0° to 60° C

Operating (Discharging) -20° to 70° C

Fuel Gauge LED NA

Warranty Depends on system offering

Optional Travel Battery

Available

Refer to http://www.hp.com/support/batterywarranty/ for battery warranty information.



<sup>\*</sup> Batteries have a default one year limited warranty except for Long Life batteries which will have same1-year or 3-year limited warranty as the platform.

### Technical Specifications – Environmental

### **ENVIRONMENTAL DATA**

## Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country.

### **System Configuration**

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

### Energy Consumption (in accordance with US ENERGY STAR® test method)

STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	7.38 W	10.02 W	7.29 W
Normal Operation (Long idle)	4.94 W	6.21 W	4.87 W
Sleep	1.69 W	1.68 W	1.59 W
Off	0.41 W	0.42 W	0.41 W

#### NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	25.24 BTU/hr	34.27 BTU/hr	24.93 BTU/hr
Normal Operation (Long idle)	16.89 BTU/hr	21.24 BTU/hr	16.66 BTU/hr
Sleep	5.78 BTU/hr	5.75 BTU/hr	5.44 BTU/hr
Off	1.4 BTU/hr	1.44 BTU/hr	1.4 BTU/hr

**\*NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions	Sound Power	Sound Pressure
(in accordance with	(L <sub>wAd</sub> , bels)	(L <sub>pAm</sub> , decibels)
ISO 7779 and ISO 9296)		
Typically Configured – Idle	2.6	14.2
Fixed Disk – Random writes	2.8	15.4
Optical Drive – Sequential reads	2.9	19.4

#### **Longevity and Upgrading**

"This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- AC adapter
- Battery
- WLAN/WWAN module
- 4 storage slots (M.2 and HDD)
- 4 SODIMM memory slots



### Technical Specifications - Environmental

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

#### **Batteries**

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Battery description: 8 cell HP Long Life Polymer 94Wh (4.15Ah)

#### **Additional Information**

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 11.09% post-consumer recycled plastic (by wt.) according to IEEE 1680.1-2018 standard, criterion 4.2.1.1.
- This product is 94.0% recycle-able when properly disposed of at end of life.

#### **Packaging Materials**

External:	PAPER/Corrugated	0.316 g
	PAPER/Molded Pulp	0.181 g
Internal:	PLASTIC/Polyethylene low density - LDPE	0.010 g
	PLASTIC/Polypropylene - PP	0.005 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 12.6 recycled content.

### **RoHS Compliance**

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industrywide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

### Technical Specifications – Environmental

#### **Material Usage**

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen\_specifications.html ):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

#### **Packaging Usage**

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

## End-of-life Management and Recycling

Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <a href="http://www.hp.com/go/reuse-recycle">http://www.hp.com/go/reuse-recycle</a> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.



### Technical Specifications – Environmental

These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

### HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

**Global Citizenship Report** 

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

**Eco-label certifications** 

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part #
Displays	HP Z32 31.5" 4k UHD Display	1AA81A8#XXX
	HP Z38c 37.5" Curved Display	Z4W65A8#XXX
Case	HP Essential Top Load Case (up to 15.6")	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Exec 17.3 Midnight Backpack	1KM17AA
	HP Business Case(up to 15.6")	2SC66AA
	HP Executive 15.6 Midnight Top Load	1KM15AA
	HP Exec 15.6 Midnight Backpack	1KM16AA
	HP Executive 15.6 Black Leather Top Load	1LG83AA
Docking	HP Adjustable Dual Monitor Stand	AW664AA
Accessories	HP Adjustable Display Stand	AW663AA
	HP Display and Notebook Stand II	E8G00AA
	HP Monitor Stand	M9X76AA
	HP Dual Hinge II Notebook Stand	E8F99AA
	HP Hot Desk Stand (up to 32" monitor)	W3Z73AA
	HP Hot Desk Stand Monitor Arm (for use with W3Z73AA; supports two 24" monitors	W3Z74AA
	HP TB Audio Module (comp with Hook dock)	3AQ21AA
	HP TB Dock G2 Combo Cable (this is 230W) comp with Hook dock	3XB96AA
Docking station	HP USB-C Mini Dock - power not supported on mWKS	1PM64AA
	HP TB Dock G2 w/ Combo Cable (this is 230W)	3TR87AA
	HP Thunderbolt Dock 230W G2	2UK38AA
	HP USB-C/A Universal Dock G2 Power Not Supported on Mobile Workstations	5TW13AA
	HP USB-C Dock G5 Power Not Supported on Mobile Workstation	5TW10AA
Input/Output -	HP Comfort Grip Wireless Mouse (See Link 5 Tab)	H2L63AA
Mice	HP 3-button USB Laser Mouse	H4B81AA
	HP Bluetooth Travel Mouse	6SP30AA
	HP USB Travel Mouse	G1K28AA
	HP Wireless Premium Mouse (See Link 5 Tab)	1JR31AA
	HP Elite Presenter Mouse	2CE30AA
Input/Output -	HP Slim USB Keyboard and Mouse	T6T83AA
Keyboard	HP Slim Wireless Keyboard and Mouse	T6L04AA
Input/Output -	HP USB-C to USB-A Hub	Z6A00AA
Adapter	HDMI to VGA Adapter	H4F02AA
	HP HDMI to DVI Adapter	F5A28AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to DisplayPort Adapter	N9K78AA
	HP USB-C to VGA Adapter	N9K76AA



<b>Options and Accessories</b>	(sold separately and	availability may vary	by country)
•	•		, ,

options and m	teessories (sold separately and availability may vary by country)	
	HP Single miniDP-to-DP Adapter Cable	2MY05AA
Collaboration	HP UC Wired Headset	K7V17AA
Memory	HP 8GB 2666Mhz DDR4	4VN06AA
	HP 16GB 2666Mhz DDR4	4VN07AA
	HP 32GB 2666MHz DDR4	6NX83AA
	HP 8GB 2666MHz DDR4 ECC	4UY11AA
	HP 16GB 2666MHz DDR4 ECC	4UY12AA
Power - A/C	HP 200W Smart AC Adapter (4.5mm)	
Adapter	HP 200W Smart AC Adapter (4.5mm)	
Adapter Dongle	HP 7.4mm to 4.5mm DC Dongle	K0Q39AA
Security	HP Essential Combination Lock	TOY16AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP Dual Head Keyed Cable Lock	T1A64AA
Storage - Externa	HP External USB DVDRW Drive	F2B56AA
Storage - SS M2	HP 256GB PCIe 3x4 NVMe SSD (2280)	V3K66AA
	HP 512GB PCIe 3x4 NVMe DS SSD (2280)	V3K67AA



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Date of change:	Version History:		Description of change:
September 11, 2020	From v1 to v2	Changed	Format
September 30, 2020	From v2 to v3	Changed	At A Glance, GRAPHICS, STORAGE AND DRIVES, SOFTWARE AND SECURITY, NETWORKING/COMMUNICATION, ENVIRONMENTAL DATA and Options and Accessories sections
October 20, 2020	From v3 to v4	Changed	Format
November 20, 2020	From v4 to v5	Changed	Format
December 1, 2020	From v5 to v6	Changed	Storage and Power sections
December 16, 2020	From v6 to v7	Added Update	BIOS Version in Software and Security section Ubuntu Linux in OPERATING SYSTEM section
December 20, 2021	From v7 to v8	Changed	NETWORKING/COMMUNICATIONS section

